

DENTON SPUTTERING LOG SHEET-Please fill out as completely as possible for characterization and maintenance purposes

Name/Phone #	Date and Log In/Out Times	Sputter Material	Substrate	Base Pressure (Torr)	Pump Down Time (hours)	Pre-Sputter		Sputter		Argon		Film Stress (Mpa)	Film Thickness (um)	Sheet Resistance (ohm/sq)	Sputter Rate (um/min)	Changed Targets?	Results/Problems/Maintenance/Etc.
						Time (min)	Time (min)	Power (W)	Pressure (mT)	Cap. Man. Flow (%)							
Hank Walker 801/8651019	8/1/00 2pm - 5pm	Si	Si	1.9	1.5	1	1	230	2500	2	2	220					
Steve PD 801/7359075	8/6 10:15 - 12:00	2nd glass	private	1.8	1.0	1	2	3	RT	13	13	13	W	ant	3		26.38 - 19.59
11	8/6 12:30 - 1:15	Si	Si	1.9	0.5	1	2	3	210	250	2	2	3				26.03
Jeff	8/6 1:15 - 2:30	Si	glass	1.8	30	1	15	2	70	150	15	15	225				
Robert Sponsler	8/6 3:00 - 3:30	Si	Si	1.9	0.5	1	2	3	230	220	2	2	220				25.81 -
Jungwoo Park	8/9 1:00pm - 3:00pm	Si	Si	1.6	0.5	1	1	1	30W	1	2	120					100W Si
Leung Sun	8/10 1:30pm - 3:00pm	Si	Si	1.6	0.5	1	2	3	15	350	3	3	30				100W Si
Hardiman	8/13 11:30 - 3:00	Si	Si	1.2	0.5	1	2	3	2	25	2	1	30				

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				Base Pressure (Torr)	Down Time (hours)	Sputter Time (min)	Sputter Time (min)	Sputter Power (W)	Pressure (mT)	Cap Man. Flow (%)							
Jing	4:15	Aln	SiO2	1e-6	10min	15min	100W	1	1	1	1						
		3Ti															
Bones	5/13/11	1Cr 2Al 3Au	SiO2	2x10 ⁻⁶	50min	1min	150W	1	1	1	1						Run checked 5/10 Resumed 5/13 Reported 2x
Rachel	5/22/11	1Si	glass	2x10 ⁻⁶	21min	1	1	1	1	1	1						
Rachel	5/22/11	2SiO2	glass	2x10 ⁻⁶	21min	2	120W	2	2	2	2						
Rachel	6/3	1Si 2SiO2 3SiO2	glass	2x10 ⁻⁶	21min 2 3	1 1 1	50 100W	1 2 3	1 2 3	1 2 3	1 2 3						
Blak	7/24/11	1Al	glass	2x10 ⁻⁶	15min	1	50	1	100W	1	1.59						
Carver	7/29/11	1Al	glass	2x10 ⁻⁶	15min	1	50	1	100W	1	1.59						
Carver	7/29/11	2Al	glass	2x10 ⁻⁶	15min	2	50	2	100W	2	1.59						
Carver	7/29/11	3Al	glass	2x10 ⁻⁶	15min	3	50	3	100W	3	1.59						

substrate blanking 200C

Blak's work on 8/11/11
2 Ti
3 Au
Software

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						Time (min)	Time (min)	Power (W)	Cap Man. (mT)	Pressure (mT)	Argon Flow (%)						
Bonnes	12/20/09	Al	SiO2	1.0	1.0	1	1	1	1	1	1	1	1	1	1	1	
Vinny	10-10-09	Si	SiO2	2.1	1.0	1	1	1	1	1	1	1	1	1	1	1	yes
Amie Smith	3/20/09	Si	SiO2	2.1	1.0	1	1	1	1	1	1	1	1	1	1	1	yes
Seavrdla	10/20/09	Si	SiO2	2.1	1.0	1	1	1	1	1	1	1	1	1	1	1	no
Freeman	3/23/09	Si	SiO2	2.1	1.0	1	1	1	1	1	1	1	1	1	1	1	yes
Jeff Johnson	1/25/09	Si	SiO2	2.1	1.0	1	1	1	1	1	1	1	1	1	1	1	yes
Jeff Johnson	2/1/09	Si	SiO2	2.1	1.0	1	1	1	1	1	1	1	1	1	1	1	yes

Jeff Johnson 3/17 was glasses 25 1 5 90 100 85 30 for

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	1				1	1	1	1	1	1	1						
	2				2	2	2	2	2	2	2						
	3				3	3	3	3	3	3	3						
	1				1	1	1	1	1	1	1						
	2				2	2	2	2	2	2	2						
	3				3	3	3	3	3	3	3						
	1				1	1	1	1	1	1	1						
	2				2	2	2	2	2	2	2						
	3				3	3	3	3	3	3	3						
	1				1	1	1	1	1	1	1						
	2				2	2	2	2	2	2	2						
	3				3	3	3	3	3	3	3						
	1				1	1	1	1	1	1	1						
	2				2	2	2	2	2	2	2						
	3				3	3	3	3	3	3	3						
	1				1	1	1	1	1	1	1						
	2				2	2	2	2	2	2	2						
	3				3	3	3	3	3	3	3						

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		1			1	1	1	1	1	1	1	1				
		2			2	2	2	2	2	2	2	2				
		3			3	3	3	3	3	3	3	3				
		1			1	1	1	1	1	1	1	1				
		2			2	2	2	2	2	2	2	2				
		3			3	3	3	3	3	3	3	3				
		1			1	1	1	1	1	1	1	1				
		2			2	2	2	2	2	2	2	2				
		3			3	3	3	3	3	3	3	3				
		1			1	1	1	1	1	1	1	1				
		2			2	2	2	2	2	2	2	2				
		3			3	3	3	3	3	3	3	3				
		1			1	1	1	1	1	1	1	1				
		2			2	2	2	2	2	2	2	2				
		3			3	3	3	3	3	3	3	3				
		1			1	1	1	1	1	1	1	1				
		2			2	2	2	2	2	2	2	2				
		3			3	3	3	3	3	3	3	3				

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Name/Phone #	Date and Log In/ Log Out Times	Sputter Material	Substrate (Torr)	Base Pressure	Pump Down Time (hours)	Pre-Sputter Time (min)	Sputter Time (min)	Sputter Power (W)	Argon Pressure Cap. Man. (mT)	Argon Flow (%)	Film Stress (Mpa)	Film Thickness (um)	4-point Sheet Resistance (ohm/sq)	Sputter Resistance Rate (um/min)	Changed Targets?	Results/Problems/Maintenance/Etc.
	1				1	1	1	1	1	1						
	2				2	2	2	2	2	2						
	3				3	3	3	3	3	3						
	1				1	1	1	1	1	1						
	2				2	2	2	2	2	2						
	3				3	3	3	3	3	3						
	1				1	1	1	1	1	1						
	2				2	2	2	2	2	2						
	3				3	3	3	3	3	3						
	1				1	1	1	1	1	1						
	2				2	2	2	2	2	2						
	3				3	3	3	3	3	3						
	1				1	1	1	1	1	1						
	2				2	2	2	2	2	2						
	3				3	3	3	3	3	3						
	1				1	1	1	1	1	1						
	2				2	2	2	2	2	2						
	3				3	3	3	3	3	3						
	1				1	1	1	1	1	1						
	2				2	2	2	2	2	2						
	3				3	3	3	3	3	3						

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					Down Time (hours)	Pre-Sputter Time (min)	Sputter Time (min)										
	1				1	1	1	1	1	1	1						
	2				2	2	2	2	2	2	2						
	3				3	3	3	3	3	3	3						
	1				1	1	1	1	1	1	1						
	2				2	2	2	2	2	2	2						
	3				3	3	3	3	3	3	3						
	1				1	1	1	1	1	1	1						
	2				2	2	2	2	2	2	2						
	3				3	3	3	3	3	3	3						
	1				1	1	1	1	1	1	1						
	2				2	2	2	2	2	2	2						
	3				3	3	3	3	3	3	3						
	1				1	1	1	1	1	1	1						
	2				2	2	2	2	2	2	2						
	3				3	3	3	3	3	3	3						
	1				1	1	1	1	1	1	1						
	2				2	2	2	2	2	2	2						
	3				3	3	3	3	3	3	3						
	1				1	1	1	1	1	1	1						
	2				2	2	2	2	2	2	2						
	3				3	3	3	3	3	3	3						
	1				1	1	1	1	1	1	1						
	2				2	2	2	2	2	2	2						
	3				3	3	3	3	3	3	3						
	1				1	1	1	1	1	1	1						
	2				2	2	2	2	2	2	2						
	3				3	3	3	3	3	3	3						
	1				1	1	1	1	1	1	1						
	2				2	2	2	2	2	2	2						
	3				3	3	3	3	3	3	3						

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Reichel	12/3	1 Al 2 Ti 3 Ni	glass	2x10 ⁻⁶	30	1	12	125	1	1	1					yes	
Barry																	
Jeff Johnson	12/15	1 no 2 3	glass	6x10 ⁻⁶	50	1	35	100	1.35	1	1						
Jeff Johnson	12/21	1 no 2 3	glass	2	60	1	2	100	1.8	1	1						
Jeff Johnson	12/22	1 no 2 3	glass	1.4	60	1	2	125	1.8	1	1						
Jeff Johnson	11/30	1 no 2 3	glass	2.5	45	1	5	50	1.9	1	1						600
Jeff Johnson	11/29	1 no 2 3	glass	2	1hr	1	2	50	1.74	1	1						600
Jeff Johnson	1/10	1 no 2 3	glass	2	1hr	1	2	50	1.74	1	1						600
Jeff Johnson	1/10	1 no 2 3	glass	2	1hr	1	2	50	1.74	1	1						600

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					Down Time (hours)	Sputter Time (min)	Sputter Time (min)	Sputter Time (min)	Sputter Power (W)	Sputter Pressure (mT)	Cap Man. Flow (%)	Film Stress (Mpa)	Film Thickness (um)	4-point Sheet Resistance (ohm/sq)	Sputter Rate (um/min)							
Jeff	11/30	2	glass	2.0	40	1	2	3	1	2	3	200	2.25	3.10	1.4	2.8	225			yes		
Jennison	11/30	3	glass	2.0	40	1	2	3	1	2	3	200	2.10	3.10	1.4	2.8	225			yes		
Jeff	11/30	1	glass	2.0	40	1	2	3	1	2	3	300	2.25	3.10	1.4	2.8	225			yes		
Johnson	11/30	2	glass	2.0	40	1	2	3	1	2	3	300	2.25	3.10	1.4	2.8	225			yes		
Blisk	11/30	1	0.0	2.0	40	1	2	3	1	2	3	100	2.10	3.10	1.4	2.8	225			yes		
Jeff	12/1	1	no glass	1.7	30	1	2	3	1	2	3	150	2.10	3.10	1.4	2.8	225			yes		
Jeff	12/2	1	no glass	2.0	40	1	2	3	1	2	3	75	1.14	2.1	1.6	2.25			yes			
Johnson	12/2	2	glass	2.0	40	1	2	3	1	2	3	100	1.1	2.1	1.8	2.25			yes			
Jeff	12/3	1	no glass	2	40	1	2	3	1	2	3	100	1.1	2.1	1.8	2.25			yes			
Johnson	12/3	2	glass	2	40	1	2	3	1	2	3	100	1.1	2.1	1.8	2.25			yes			
New Key	12/19	1	0		20	1	1	3	1	1	3	400	1.20	3.10	1.50	2.00			yes			
Jeff	12/4	1	2	glass	2	40	1	2	3	1	2	350	1.60	1.2	2.5	2.00			yes			
Johnson	12/4	2	glass	2	40	1	2	3	1	2	3	350	1.60	1.2	2.5	2.00			yes			
Jeff	12/10	1	0		100	1	1	3	1	1	3	350	1.20	2.4	1.90	2.00			yes			
Johnson	12/10	2	no glass	0	100	1	1	3	1	1	3	350	1.20	2.4	1.90	2.00			yes			

Teff Johnson 11/11 no glass 1.6 30 5 5 100 3.3 25%

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						Time (min)	Time (min)	Power (W)	Cap Man. (%)	Pressure (mT)	Flow (%)								
801-587-5335																			
Teff Johnson	10/27 10:30	1	no glass	1.6	30	1	5	1	12	1	900	1	4.5	1.50					Y
	10:30	2				2	2	2	12	2	300	2	4.4	1.30					
	10:30	3				3	3	3	15	3	300	3	5	3.10					Y
	11:13	1	no glass	1.6	30	1	3	1	12	1	200	1	4.4	1.30					Y
	10:00	2				2	2	2	12	2	300	2	5	3.10					
	10:00	3				3	3	3	15	3	300	3	5	3.10					
	11:13	1	no glass	1.4	30	1	3	1	12	1	200	1	2	1.23					Y
	10:30	2				2	2	2	12	2	300	2	2	1.23					
	12:30	3				3	3	3	12	3	300	3	3	1.23					
David W Johnson	10/29 9:40	1	no glass	1.6	30	1	1	1	12	1	46	1	1	1.30					Y
	10:29	2				2	2	2	12	2	46	2	2	1.30					
	9:40	3				3	3	3	12	3	46	3	3	1.30					
Teff Johnson	11/4	1	no glass	1	14-2	3	1	1	60	1	255	1	45	1.88					
	11/4	2				2	3	2	60	2	255	2	45	1.88					
	11/4	3				3	3	3	60	3	255	3	45	1.88					
Teff Johnson	11/5 12:00	1	no glass	1.6	30	1	3	1	50	1	75	1	3	1.5					Y
	12:00	2				2	2	2	50	2	75	2	3	1.5					
	12:00	3				3	3	3	50	3	75	3	3	1.5					
Teff Johnson	11/5 12:00	1	no glass	1.6	30	1	0	1	50	1	200	1	2.5	1.5					Y
	12:00	2				2	0	2	50	2	200	2	2.5	1.5					
	12:00	3				3	3	3	50	3	200	3	3	1.5					
David W Johnson	11/9 9 am	1	no glass	1.6	30	1	1	1	12	1	43	1	1	1.7					Y
	11/9	2				2	1	2	12	2	43	2	2	1.7					
	11/9	3				3	2	3	12	3	43	3	3	1.7					
Teff Johnson	11/10 10:10	1	no glass	1.6	40	3	50	75	5	3	376	3	3	3					Y
	11/10	2				2	50	75	5	3	376	2	3	3					
	11/10	3				3	50	75	5	3	376	3	3	3					

This log sheet is now on the computer

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	1	2					Time (min)	Time (min)	Power (W)	Cap Man. (mT)	Argon Flow (%)	Film Stress (Mpa)	Film Thickness (um)	Sheet Resistanc (ohm/sq)								
Kosun	09/06/10	8:30	Si	Si	2e-6	hr	1	20	3	1	20	2	3	2	3	2	3	2	3	2	3	OK sputter not targeted for Si3N4
Kosun	09/06/10	9:00	Ni	Si	2e-6	hr	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3	
Kosun	09/06/10	11:30	Ni	Si	2e-6	hr	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3	
Kosun	09/06/10	4:00	Ni	Si	1.5e-6	hr	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3	
Tungsten	09/06/10	6:00	Ni	Si	2e-6	hr	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3	
Tungsten	09/06/10	9:30	Cr	SiO2	2e-6	hr	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3	Yes
Tungsten	09/06/10	4:45	Cr	SiO2	2e-6	hr	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3	(cell #3) sputtering does not work
Kosun	09/08/10	5:15	Si	Si	2e-6	hr	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3	
Kosun	09/08/10	5:30	Si	Si	1.5e-6	hr	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3	
Kosun	09/10/10	18:00	Si	Si	1.8e-6	hr	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3	
Kosun	09/10/10	6:00	Si	Si	2e-6	hr	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3	

PLEASE fill out Both

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	Log In	Log Out															
801-706-3001	3:00 PM	3:00 PM	Cr	Si	2.0	40	1	1	1.5	1.5	120%	0.01	0.2			Yes	
801-706-3001	3:00 PM	3:00 PM	Cr	Si	2.0	40	1	1	1.5	1.5	120%	0.01	0.2			Yes	

801-680-7095	1 PM	1 PM	Al	Sapphire	1.6	45	1	1	1.5	1.5	150%	0.15	0.03				
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801-706-3011	1:00 AM	1:00 AM	Al	wafer	1.8	40	1	1	1.5	1.5	150%	0.05	0.06			Yes	
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801-706-3009	5:30 PM	5:30 PM	Si	Si	1.6	40	1	1	1.5	1.5	150%	0.03	0.03				
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801-706-3009	3:45	3:45	Si	Glass	2.1	45	1	1	1.5	1.5	150%	0.03	0.03			Yes	
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801-706-3009	8:11	8:11	Si	Si	1.5	40	1	1	1.5	1.5	150%	0.03	0.03				
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David W	9-2	9-2	Al	Glass slides	2.1	40	1	1	1.5	1.5	150%	0.03	0.03			Yes	Completed
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Korn	4:00	4:00	Al	Si	2.1	45	1	1	1.5	1.5	150%	0.03	0.03				
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David W	9-9	9-9	Al	Glass slides	2.1	40	1	1	1.5	1.5	150%	0.03	0.03			Yes	
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DENTON SPUTTERING LOG SHEET-Please fill out as completely as possible for characterization and maintenance purposes

Name/Phone #	Date and Log In/ Log Out Times		Sputter Material	Substrate (Torr)	Base Pressure (Torr)	Pump Down Time (hours)	Pre-Sputter Time (min)		Sputter Time (min)		Sputter Power (W)	Argon Pressure Cap.Man. Flow (mT) (%)		Film Stress (Mpa)	Film Thickness (um)	4-point Sheet Resistance (ohm/sq)	Sputter Rate (um/min)	Changed Targets?	Results/Problems/Maintenance/Etc.	
	1	2					1	2	1	2		1	2							
Korn	7:00	8:00	W	S ₂ N ₂	10 ⁻⁶	45	2	2	7	2	25	2	2	2	2	2	2	2		
	8:00																			
Champion	9/13/10		Cr	Tethon	Lo	10	1	1	2	2	40	2	2	2	2	2	2	2		
	11:00		Ag				3	1	3	7	3	50	3	3	3	3	3	3		
Park	11:30		Ag	Tethon	2 nd	20	2	1	2	7	2	90	2	2	2	2	2	2		
	12:30						3	1	3	7.5	3	50	3	3	3	3	3	3		
Korn	09/14/10		Cr	S ₂ N ₂	10 ⁻⁶	30	1	1	1	1	500	2	2	2	2	2	2	2		
	11:00						3	2	2	3	3	50	3	3	3	3	3	3		
	12:00																			
Korn	09/14/10		Cr	S ₂ N ₂	20 ⁻⁶	40	1	1	1	1	50	2	2	2	2	2	2	2		
	12:00						3	2	2	3	3	50	3	3	3	3	3	3		
Korn	09/17/10		N ₂	S ₂ N ₂	21 ⁻⁶	45	1	1	2	4	250	2	2	2	2	2	2	2		
	1:00						3	2	2	3	3	50	3	3	3	3	3	3		
Korn	09/21/10		Cr	Cr	20 ⁻⁶	35	1	1	1	7	2	40	2	2	2	2	2	2		
	1:00						3	2	2	3	3	50	3	3	3	3	3	3		
Shoy	09/22/10		Ti	Sputter	20 ⁻⁶	1	1	1	1	1	100	2	2	2	2	2	2	2		
	5:30						3	1	3	1	3	100	3	3	3	3	3	3		
Korn	09/24/10		Cr	S ₂ N ₂	10 ⁻⁶	60	1	1	2	4	2	50	2	2	2	2	2	2		
	7:30						3	2	2	3	3	50	3	3	3	3	3	3		
	8:00																			

Cr → Ag
 Cr → Ag
 Cr → Ag

DENTON SPUTTERING LOG SHEET-Please fill out as completely as possible for characterization and maintenance purposes

Name/Phone #	Date and Log In/Out Times		Sputter Material	Substrate	Base Pressure (Torr)	Pump Down Time (hours)	Sputter Pre-Time (min)	Sputter Time (min)	Sputter Power (W)	Argon			Film Stress (Mpa)	Film Thickness (um)	4-point Sheet Resistance (ohm/sq)	Sputter Rate (um/min)	Changed Targets?	Results/Problems/Maintenance/Etc.	
	1	2								3	1	2							3
Kevin	9/27	11:30	BN	BN	1.5e-6	2	2	1:30	225	1	2	3	2.5%						
Kevin	9/28	6:00	BN	BN	2e-6	1	2	2:30	225	1	2	3	2%						
Kevin	9/29	9:00	BN	BN	2.5e-6	1	2	2:30	225	1	2	3	3.5%						
David	9/27	12:00	Glass	Glass	2e-6	2	3	1:45	45	1	2	3	2%						
Kevin	9/28	1:30	BN	BN	2e-6	1	2	3:30	225	1	2	3	2.5%						
Kevin	9/28	4:00	BN	BN	2e-6	1	2	3:30	225	1	2	3	3%						
Kevin	9/28	5:30	BN	BN	2e-6	1	2	3:30	225	1	2	3	3%						
Kevin	9/28	7:30	BN	BN	2e-6	1	2	3:30	225	1	2	3	3%						
Kevin	9/28	11:30	BN	BN	2e-6	1	2	3:30	225	1	2	3	3%						

DENTON SPUTTERING LOG SHEET-Please fill out as completely as possible for characterization and maintenance purposes

Name/Phone #	Date and Log In/ Times	Sputter Material	Substrate	Base Pressure (Torr)	Pump Down Time (hours)	Pre-Sputter			Sputter			Argon			Film Stress (Mpa)	Film Thickness (um)	4-point Sheet Resistance (ohm/sq)	Sputter Rate (um/min)	Changed Targets?	Results/Problems/Maintenance/Etc.
						Time (min)	Power (W)	Pressure (mT)	Time (min)	Power (W)	Pressure (mT)	Flow (%)	Flow (%)							
Hannum 808320 38664	9/3/12 12:00 2:30	Cr	Si	2e-6	60	1	25	1	2	150	1	1	25%	1	2	1			N	
Keen	01/29 2:40 -1:00	Si	glass	1.8e-6	1hr	2	10	300	1	1	1	1	30%	1	2	3			Y	
Hannum 808320 38664	9/21 6:10 6:40	Cr	Si	1.8e-6	60	1	2	350	1	2	1	1	25%	1	2	3			N	
Hannum 708320 38664	11:30 1:50 3:00	Cr	Si	1.8e-6	45	2	2	250	1	2	1	1	25%	1	2	3			Y	
Hannum Storaker 801851073	3:00PM 5PM	Cr	Si	2.1e-6	40	1	2	250	1	2	1	1	25%	1	2	3			Y	Problem with cathode 2
Hannum 808320 38664	3AM 3	Cr	Si	1.8e-6	50	2	2	500	1	2	1	1	25%	1	2	3			Y	
Hannum 808320 38664	2:00 3	Cr	Si	2.1e-6	45	2	2	250	1	2	1	1	25%	1	2	3			N	
Hannum 808320 38664	2:40 2:05 3	Cr	Si	1.5e-6	60	2	2	250	1	2	1	1	25%	1	2	3			N	
Jung Woo Park	10/2/10 1:00PM 2:00PM 3AM	Cr	Si	2.0e-6	30	1	2	300	1	2	1	1	25%	1	2	3			Y	Cathode 1 plasma ignition problem

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Name/Phone #	Date and Log In/Out Times		Sputter Material	Substrate	Base Pressure (Torr)	Pump Down Time (hours)	Pre-Sputter Time (min)	Sputter Time (min)	Sputter Power (W)	Argon		Film Stress (Mpa)	Film Thickness (um)	4-point Sheet Resistance (ohm/sq)	Sputter Rate (um/min)	Changed Targets?	Results/Problems/Maintenance/Etc.
	Cap. Man. (mT)	Flow (%)															
Medium 906370 8864	10/02	2:33	W	Si	1.80 ⁻⁶	6:55	2	2	2	3	50	2	3	2	2	Y	
Medium 906370 8864	10/02	4:00	W	Si	1.80 ⁻⁶	6:55	2	2	2	3	50	2	3	2	2	Y	
Medium 906370 8864	10/04	2:33	W	Si	1.80 ⁻⁶	6:55	2	2	2	3	50	2	3	2	2	Y	
Medium 906370 8864	10/04	7:00	W	Si	1.68 ⁻⁶	1:44	2	2	2	3	50	2	3	2	2	Y	
Medium 906370 8864	10/05	12:00	W	Si	1.80 ⁻⁶	5:0	2	2	2	3	50	2	3	2	2	Y	
Medium 906370 8864	10/06	11:30	W	Si	1.80 ⁻⁶	6:55	2	2	2	3	50	2	3	2	2	Y	
Medium 906370 8864	10/06	6:30	W	Si	1.80 ⁻⁶	6:55	2	2	2	3	50	2	3	2	2	Y	
Medium 906370 8864	10/06	7:45	W	Si	1.80 ⁻⁶	6:55	2	2	2	3	50	2	3	2	2	Y	
Medium 906370 8864	10/07	2:30	W	Si	1.80 ⁻⁶	6:55	2	2	2	3	50	2	3	2	2	Y	
Medium 906370 8864	10/07	4:00	W	Si	1.80 ⁻⁶	6:55	2	2	2	3	50	2	3	2	2	Y	
Medium 906370 8864	10/07	2:30	W	Si	1.80 ⁻⁶	6:55	2	2	2	3	50	2	3	2	2	Y	
Medium 906370 8864	10/07	4:00	W	Si	1.80 ⁻⁶	6:55	2	2	2	3	50	2	3	2	2	Y	
Medium 906370 8864	10/07	2:30	W	Si	1.80 ⁻⁶	6:55	2	2	2	3	50	2	3	2	2	Y	
Medium 906370 8864	10/07	4:00	W	Si	1.80 ⁻⁶	6:55	2	2	2	3	50	2	3	2	2	Y	
Medium 906370 8864	10/07	2:30	W	Si	1.80 ⁻⁶	6:55	2	2	2	3	50	2	3	2	2	Y	
Medium 906370 8864	10/07	4:00	W	Si	1.80 ⁻⁶	6:55	2	2	2	3	50	2	3	2	2	Y	

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Name/Phone #	Date and Log In/ Log Out Times	Sputter Material	Substrate	Base Pressure (Torr)	Pump Down Time (hours)	Pre-Sputter			Sputter			Argon			Film Stress (Mpa)	Film Thickness (um)	4-point Sheet Resistance (ohm/sq)	Sputter Rate (um/min)	Changed Targets?	Results/Problems/Maintenance/Etc.
						Time (min)	Time (min)	Power (W)	Cap Man. (mT)	Flow (%)	Pressure (mT)	Flow (%)	Stress (Mpa)							
Jungwoo 801-587-8305	9/22/00 14:00	Cr Au	Teflon 1		30 min	1	2	3	1	2	3	1	2	3					Yes	
David W 801-587-8305	9/23 11:00	Cr Au	SiO2		20 min	1	2	3	1	2	3	1	2	3					Yes	

David W	9/23 11:00	Cr Au	SiO2		20 min	1	2	3	1	2	3	1	2	3					Yes	
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Sang-Yun Lee	9/23 11:00	Cr Au	SiO2		20 min	1	2	3	1	2	3	1	2	3					No	
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Jungwoo 801-587-8305	9/23 11:00	Cr Au	SiO2		20 min	1	2	3	1	2	3	1	2	3					Yes	
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Jelt Johnson 8305	9/24 11:00	Cr Au	SiO2		30 min	1	2	3	1	2	3	1	2	3					Yes	RF
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Lee	9/24 11:00	Cr Au	SiO2		30 min	1	2	3	1	2	3	1	2	3					DC	
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Lawrence 806-510-8864	9/24 11:00	Cr Au	SiO2		30 min	1	2	3	1	2	3	1	2	3					Yes	
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David W 801-587-8305	9/24 11:00	Cr Au	SiO2		30 min	1	2	3	1	2	3	1	2	3					Yes	
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